



Material Content Data Sheet



Sales Product Name		ICE3BR1065J		Issued		29. August 2013		
MA#		MA001118930						
Package		PG-DIP-8-13		Weight*		557.44 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	4.412	0.79	0.79	7914	7914
leadframe	inorganic material	phosphorus	7723-14-0	0.054	0.01		96	
	non noble metal	zinc	7440-66-6	0.215	0.04		385	
	non noble metal	iron	7439-89-6	4.297	0.77		7708	
wire	non noble metal	copper	7440-50-8	174.475	31.30	32.12	312995	321184
	noble metal	gold	7440-57-5	0.297	0.05	0.05	532	532
	encapsulation	organic material	carbon black	1333-86-4	1.090	0.20		1956
encapsulation	plastics	epoxy resin	-	35.254	6.32		63243	
	inorganic material	silicondioxide	60676-86-0	327.098	58.69	65.21	586789	651988
leadfinish	non noble metal	tin	7440-31-5	7.496	1.34	1.34	13447	13447
plating	noble metal	silver	7440-22-4	0.796	0.14	0.14	1428	1428
glue	plastics	epoxy resin	-	0.293	0.05		526	
	noble metal	silver	7440-22-4	1.662	0.30	0.35	2981	3507
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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